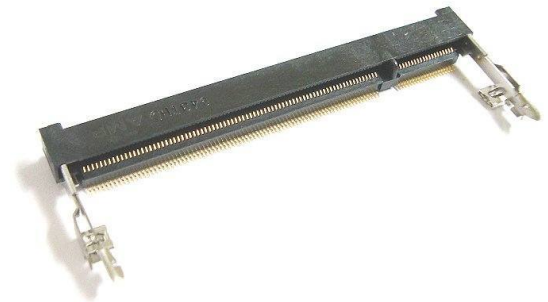
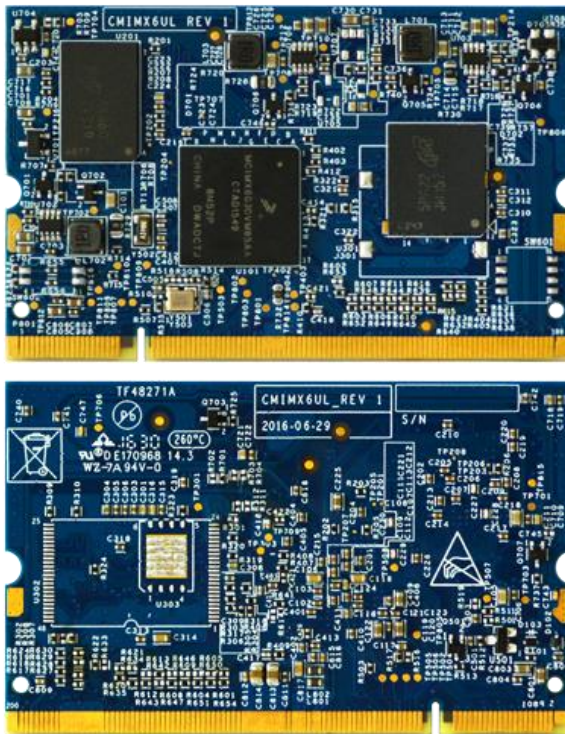


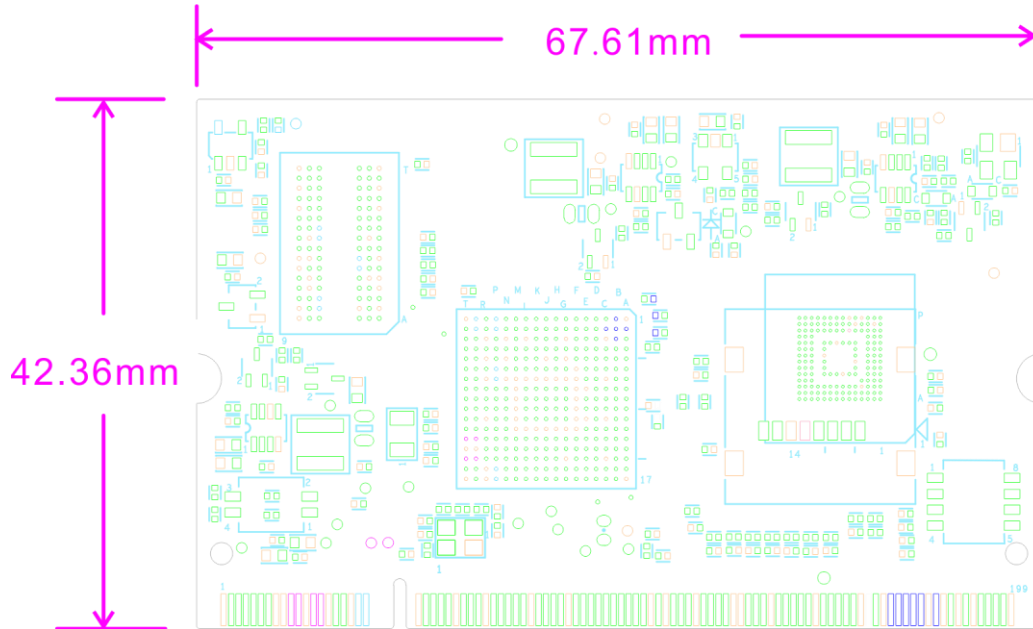
CM6ul *Computer-on-Module*

Interface Connection



1 PCB Dimension

Figure 1. PCB Dimension

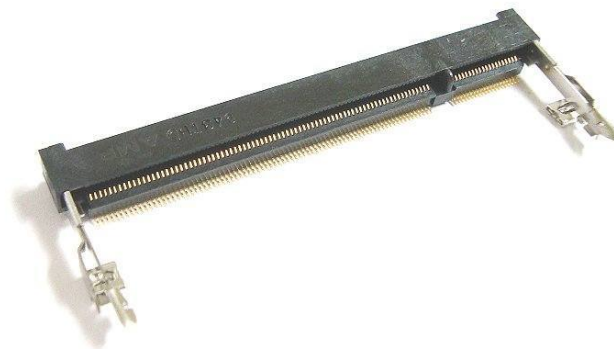


2 Interface Connection

The baseboard uses a 200 pin SODIMM card edge interface for CPU board interfacing.

2.1 SODIMM200 Card Edge Socket Specifications

Figure 2. SODIMM Socket (1.8V, H=5.2mm, on the baseboard)



SPECIFICATIONS

DDR II SO DIMM Connectort

Mechanical

Contact Retention Force: 0.10kg min. **4.0 mm Height SMT Type** **Durability :** 25 Cycles **0.6mm**
[.024"] Pitch

AS Series

200Pos.

Electrical

Voltage Rating: 25V

Current Rating: 0.3A

Contact Resistance: 50mW max.

Dielectric Withstanding Voltage: 250V AC/1 min.

Insulation Resistance: 100MW

Physical

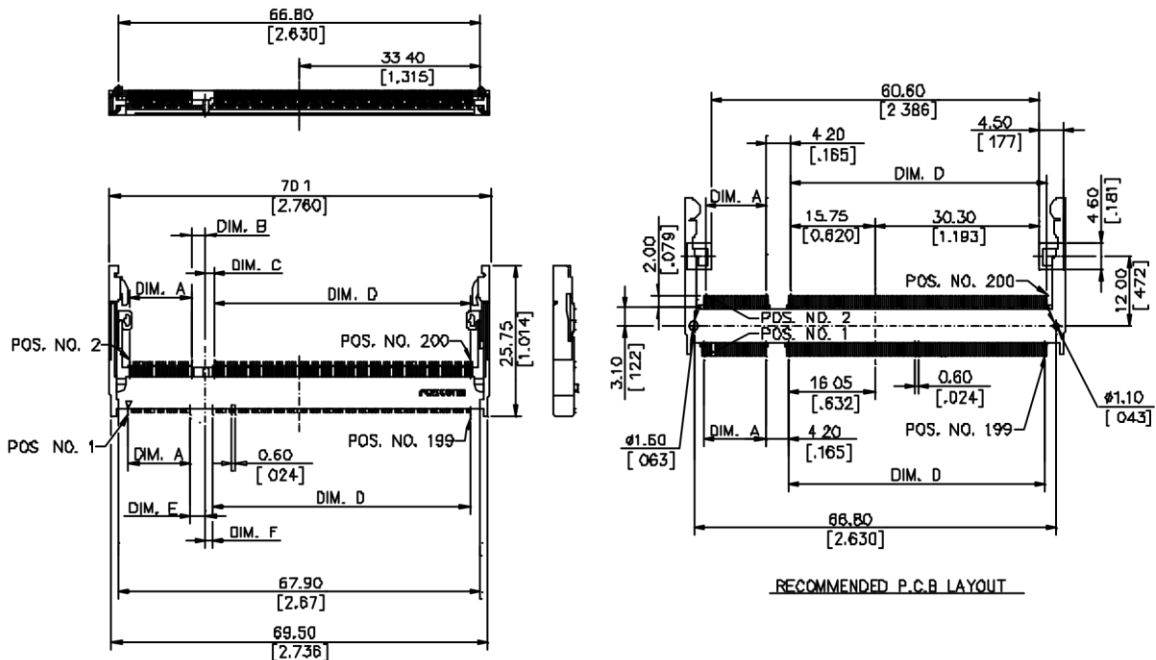
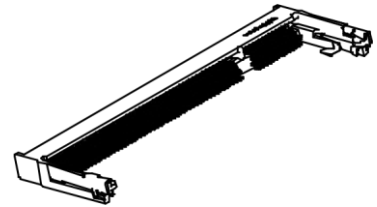
Housing: Thermoplastic, UL 94V-0 rated in Ivory Color

Contact: Copper alloy

Plating: See "ORDERING INFORMATION"

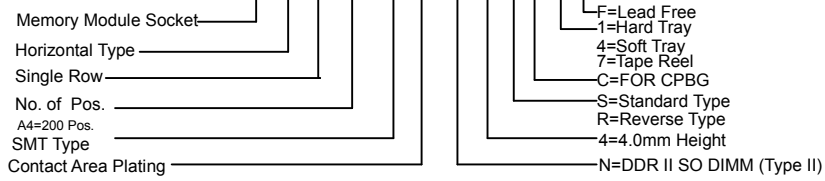
Metal Spring: Copper alloy

Operating Temperature: -40□ to +85□



PRODUCT

NO.: A S 0 A4 2 6 - N 4 * C - * F



6=10u" Gold

ASDA426-N4RN-*F	11.40 [.449]	1.80 [.071]	2.40 [.094]
ASDA426-N4SN-*F	47.40 [1.866]	2.70 [.108]	1.50 [.059]
P/N	DIM. D	DIM. E	DIM. F
ASDA426-N4RN-*F	47.40 [1.866]	1.50 [.059]	2.70 [.108]
ASDA426-N4SN-*F	11.40 [.449]	2.40 [.094]	1.80 [.071]
P/N	DIM. A	DIM. B	DIM. C

All specification & dimensions are subject to change, please call your nearest Foxconn sales representative for update information.